Ideal for High Density Applications Such as Smartphones

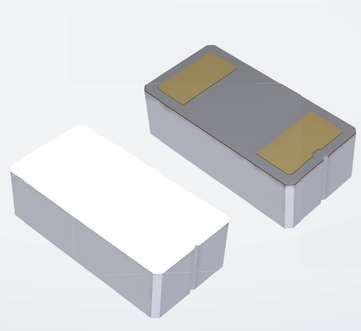
UNDER DEVELOPMENT

The Industry's Smallest Class of Overcurrent Protection Elements

SMF1005

Features

- Original process technology results in the smallest form factor in the industry : 1.0mm × 0.5mm
- Gold electrodes are adopted that provide excellent corrosion resistance and improve reliability and solder wettability
- High-speed operation

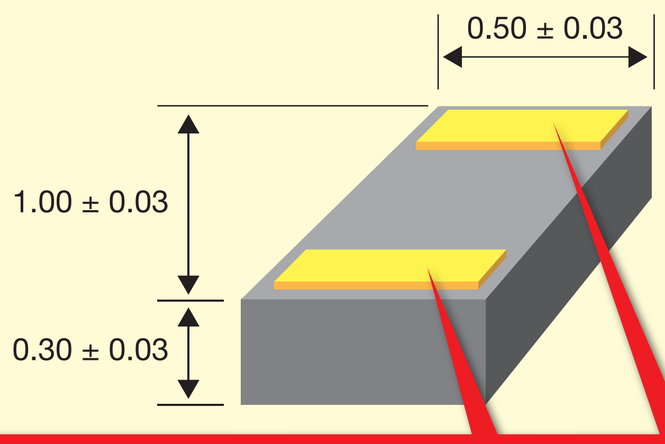


CSP

Applications

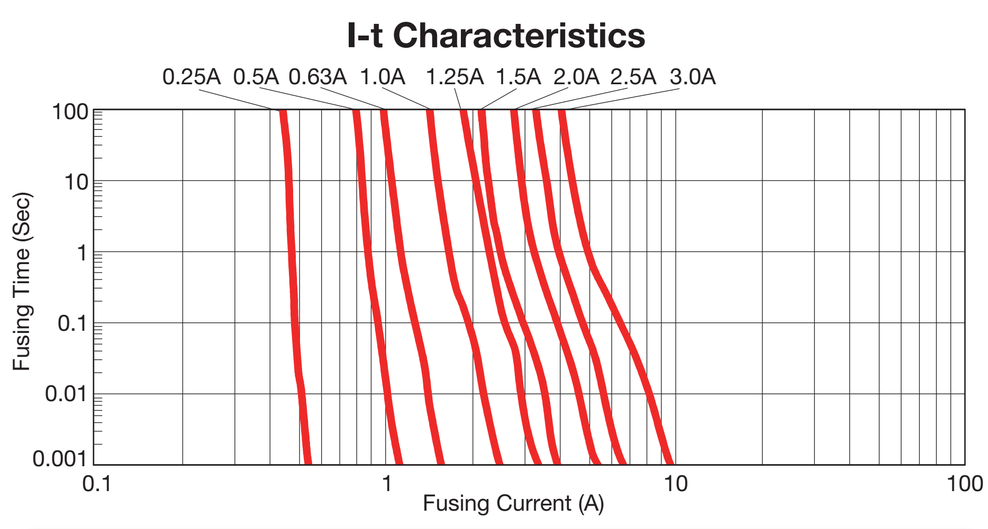
- Smartphones
- Digital cameras
- Tablet PCs

Dimensions (unit : mm)



Utilizing gold electrodes with excellent corrosion resistance improves reliability and solder wettability

Electrical Characteristics



Superior protection

*The above characteristics are intended for reference purposes only and are not guaranteed

Lineup

Part No.	Rated Current (A)	Internal Resistance (mΩ) (Typ.)	Fusing Current	Rated Capacity (VDC / A)	Operating Temperature (°C)	Residual Resistance (kΩ)
☆ ICP-R0.25	0.25	840	Max 5sec at Rated Current × 200%	32 / 35	-55 to +125	10 over
☆ ICP-R0.5	0.5	370				
☆ ICP-R0.63	0.63	320				
☆ ICP-R1.0	1.0	170				
☆ ICP-R1.25	1.25	112				
☆ ICP-R1.5	1.5	95				
☆ ICP-R2.0	2.0	60				
☆ ICP-R2.5	2.5	44				
☆ ICP-R3.0	3.0	35				

☆ : Under development